Special Issue

CMOS-MEMS Fabrication Technologies and Devices, 2nd Edition

Message from the Guest Editor

Electronics are extremely popular in our daily life. Semiconductors such as complementary metal oxide semiconductor (CMOS) and micro-electro-mechanical system (MEMS) are key devices in the electronic field. CMOS can be integrated with MEMS components within a single chip (3D integration) to produce compact and low-cost CMOS-MEMS devices for multiple applications (sensing, detection, imaging, signal transmission, and others). Therefore, these devices' fabrication and integration are essential for the development of modern society. This Special Issue aims to gather high quality research contributions dealing with MEMS devices integrated with CMOS, independently of fabrication technologies and final applications.

Guest Editor

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Editor-in-Chief

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